

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2471	"156"/\$.ccls. and (control\$5) and (stretch)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:55
L2	2	"156"/\$.ccls. and ((correct or correcting or correction) near2 (value or figure or amount)) and (load near2 (deviation or modification or aberration or aberation or change or adjustment)) and (pcb or (circuit near2 board))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:56
L3	19	"156"/\$.ccls. and (control\$5) and (flexure) and (pcb or (circuit near2 board))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:56
L4	7290778	JP 11-54877	JPO	OR	OFF	2005/04/17 13:55
L5	0	11-54877	JPO	OR	OFF	2005/04/17 13:55
L6	0	11-054877	JPO	OR	OFF	2005/04/17 13:55
L7	0	h11-054877	JPO	OR	OFF	2005/04/17 13:55
L8	0	"054877"	JPO	OR	OFF	2005/04/17 13:55
L9	96	(display near3 panel) and ((heating or heater or weld or welding or bond or bonding) near2 head) and control and (stretch or deviation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/17 13:55
L10	1	"11054877"	JPO	OR	OFF	2005/04/17 13:55
L11	1	("5243755").PN.	USPAT; USOCR	OR	OFF	2005/04/17 13:55
L12	94	(100/51).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:55
L13	41	"156"/\$.ccls. and (control\$5) and (load near2 (deviation or modification or aberration or aberation or change or adjustment)) and (semiconductor or IC or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:55

L14	41	"156"/\$.ccls. and (control\$5) and (stretch) and (pcb or (circuit near2 board))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:55
L15	8	"156"/\$.ccls. and (control\$5) and (load near2 (deviation or modification or aberration or aberation or change or adjustment)) and (pcb or (circuit near2 board))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:55
L16	85	"156"/\$.ccls. and ((heating or heater or weld or welding or bond or bonding) near2 head) and control and (stretch or deviation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/17 13:55
L17	79	"156"/\$.ccls. and (control\$5) and (flexure) and (semiconductor or IC or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:55
L18	3	(("5858806") or ("5243735") or ("6458236")).PN.	USPAT; USOCR	OR	OFF	2005/04/17 13:55
L19	3	(("5858806") or ("5243755") or ("6458236")).PN.	USPAT; USOCR	OR	OFF	2005/04/17 13:55
L20	19	(display near3 board) and ((heating or heater or weld or welding or bond or bonding) near2 head) and control and (stretch or deviation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/17 13:55
L21	120	(100/46).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:55
L22	164	"156"/\$.ccls. and (control\$5) and (stretch) and (semiconductor or IC or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:55
L23	272	(156/360).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:55

L24	228	(156/379).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:55
L25	238	(100/47).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:55
L26	353	(100/48).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:55
L27	317	(100/50).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:55
L28	360	(438/7).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:55
L29	416	(156/358).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:55
L30	447	(156/351).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:55
L31	508	(156/359).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:55

L32	785	(156/378).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:55
L33	1009	(438/16).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:55
L34	1372	(156/64).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:55
L35	129	(control\$5) and (load near2 (deviation or modification or aberration or aberation or change or adjustment)) and (pcb or (circuit near2 board)) and (bond or bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:55
L36	214	(control\$5) and (load near2 (deviation or modification or aberration or aberation or change or adjustment)) and (pcb or (circuit near2 board)) and (bond or bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/17 13:55
L37	2355	(bond or bonding or solder) and (control\$5) and (flexure) and (semiconductor or IC or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:55
L38	82	thermocompression and (control\$5) and (flexure) and (semiconductor or IC or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:55
L39	5	(control\$5) and (load near2 (deviation or modification or aberration or aberation or change or adjustment)) and (pcb or (circuit near2 board)) and (thermocompression)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:55
L40	5	(control\$5) and (load near2 (deviation or modification or aberration or aberation or change or adjustment)) and (pcb or (circuit near2 board)) and (thermocompression)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/17 13:55

L41	273	(29/877).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:55
L42	3	L41 and (thermocompression)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/17 13:55
S75	271	(29/877).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/17 13:56